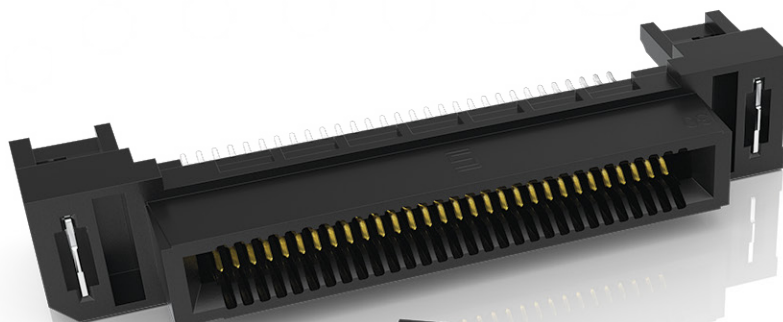


GENERATE[®]

HIGH-SPEED EDGE CARD SYSTEMS

0.60 mm, 0.80 mm and 1.00 mm PITCH

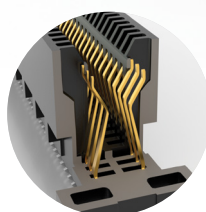
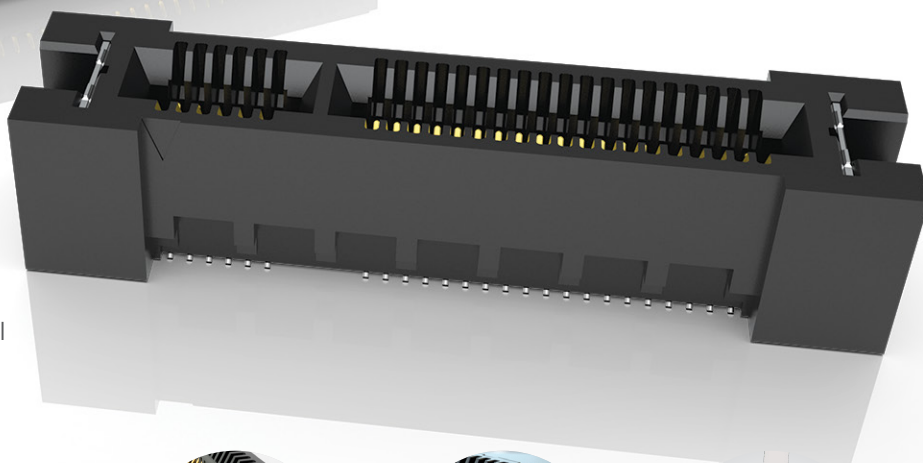


**EDGE
RATE[®]**
CONTACT

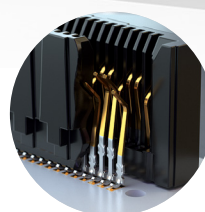
FEATURES & BENEFITS

- Maximum Design Flexibility
- Up to 64 Gbps PAM4 performance
- PCI Express[®] 3.0, 4.0, 5.0 and 6.0
- Edge Rate[®] contacts optimized for signal integrity performance and high-cycle life
- Up to 200 positions available
- Vertical, right-angle, edge mount, pass-through orientations
- Power/signal combo, press-fit tails, rugged weld tabs, locks and latches
- Mating cable assemblies available

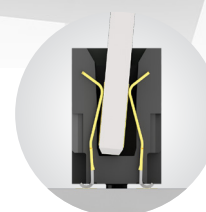
The PCI Express[®] design marks are registered trademarks and/or service marks of PCI-SIG.



Rugged tucked
beam technology
(HTEC8)



Differential pair for
increased speed
(HSEC8-DP)



Custom designs allow
for misalignment in
the X-Y axes (HSEC1)

KEY SPECIFICATIONS

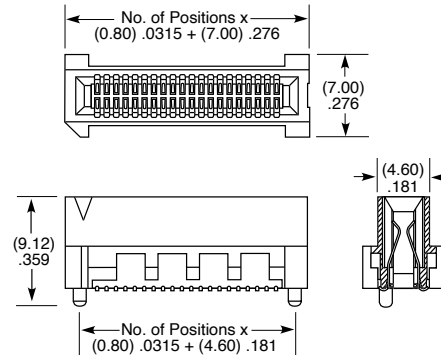
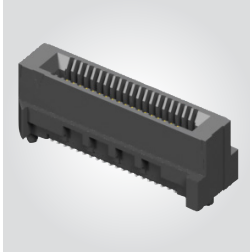
SERIES	PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
HSEC6	0.60 mm	56-168	Black LCP	Copper Alloy	-55 °C to +125 °C	1.9 A (2 pins)	240 VAC/339 VDC	Yes
HTEC8	0.80 mm	20-200	Black LCP	Copper Alloy	-55 °C to +125 °C	3.0 A (2 pins)	215 VAC/304 VDC	Yes
HSEC8-DV	0.80 mm	18-200	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-RA	0.80 mm	18-120	Black LCP	BeCu	-55 °C to +125 °C	2.6 A (2 pins)	175 VAC/247 VDC	Yes
HSEC8-EM	0.80 mm	20-120	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-PE	0.80 mm	20-40	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-PV	0.80 mm	40-80	Black LCP	BeCu	-55 °C to +125 °C	3.2 A (2 pins)	215 VAC/304 VDC	Yes
HSEC8-DP	0.80 mm	16-112	Black LCP	BeCu	-55 °C to +125 °C	2.7 A (2 pins)	235 VAC/332 VDC	Yes
HSEC1	1.00 mm	20-140	Black LCP	Phosphor Bronze	-55 °C to +125 °C	2.2 A (2 pins)	215 VAC/304 VDC	Yes

(0.80 mm) .0315" PITCH • PASS-THROUGH & POWER COMBO

HSEC8	1	POSITIONS PER ROW	CARD THICKNESS	PLATING OPTION	DV	A	PE	OTHER OPTIONS	"X"R
		10, 13, 20	-01 = (1.60 mm) .062" thick card	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on tail				-K = (5.50 mm) .217" DIA Polyimide Film Pick & Place Pad	Leave blank for Tray Packaging -TR =Tape & Reel Packaging -FR = Full Reel Tape & Reel Packaging (Must order max. quantities per reel. Contact Samtec for parts per reel)

HSEC8-PE

Card Mates:
(1.60 mm) .062" thick card, HSC8



ALSO AVAILABLE

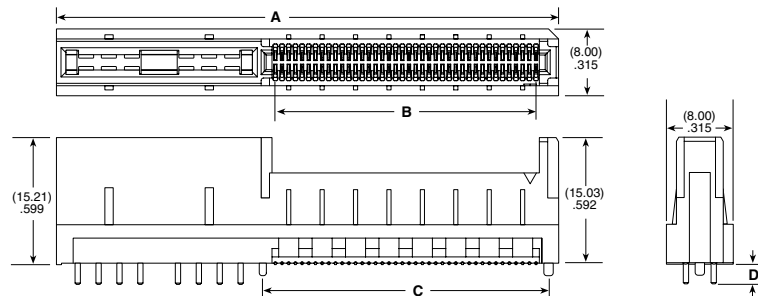
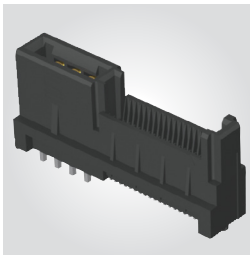
1.00 mm High-Speed Micro Plane Socket.
View complete specifications at samtec.com?SAL1

View complete specifications at: samtec.com?HSEC8-DV

HSEC8	1	SIGNAL POSITIONS	CARD THICKNESS	PLATING OPTION	PV	POWER POSITIONS	POWER TAIL	OTHER OPTION
		20, 30, 40 (Signal positions per row)	-01 = (1.60 mm) .062" thick card	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on tail		-2, -4 (Total, 2 per power bank)	-1 = Use with (1.60 mm) .062" Thick PCB -2 = Use with (2.36 mm) .093" Thick PCB	-WT = Weld Tab

HSEC8-PV

Card Mates:
(1.60 mm) .062" thick card



SIGNAL POSITIONS	POWER POSITIONS						POWER TAIL	D
	A (-2)	B (-2)	C (-2)	A (-4)	B (-4)	C (-4)		
20	(32.10) 1.264	(15.20) .598	(18.20) .717	(44.10) 1.736	(15.20) .598	(18.20) .717	-1	(2.35) .093
30	(40.10) 1.579	(23.20) .913	(26.20) 1.031	(52.10) 2.051	(23.20) .913	(26.20) 1.031	-2	(3.13) .123
40	(48.10) 1.894	(31.20) 1.228	(34.20) 1.346	(60.10) 2.366	(31.20) 1.228	(34.20) 1.346		

Note:
Some sizes, styles and options are non-standard, non-returnable.

View complete specifications at: samtec.com?HSEC8-PV